Pin Configuration

64-TSSOP

Frequency Select Table

riequency	Select la	DIE		
FS∟2	FS _L 1	FS _L 0	Input	DIF_x;
B0b2	B0b1	B0b0	MHz	MHz
0	0	0	266.66	266.66
0	0	1	133.33	133.33
0	1	0	200.00	200.00
0	1	1	166.66	166.66
1	0	0	333.33	333.33
1	0	1	100.00	100.00
1	1	0	400.00	400.00
1	1	1	Hi-Z	Hi-Z

^{1.} FS₁ (2:0) are 3.3V tolerant low-threshold inputs.

Please see VIL_FS and VIH_FS specifications in

the Input/Supply/Common Output Parameters Table for correct values.

SMBus Address Selection (Pin 29)

ADR_SEL	Voltage	SMBus Adr (Wr/Rd)
Low	<0.8V	DC/DD
Mid	1.2 <vin<1.8v< td=""><td>D6/D7</td></vin<1.8v<>	D6/D7
High	Vin > 2.0V	D4/D5

Power Groups

Pin N	lumber	Description			
VDD	GND				
1	4	DIF_IN/DIF_IN#			
8, 17, 24, 41, 48, 57	9, 16, 25, 40, 49, 56	DIF(11:0)			
N/A	63	IREF			
64	63	Analog VDD & GND for PLL core			

Note: Please treat pin 1 as an analog VDD.

^{**} Indicates 120K ohm Pulldown

Pin Description

PIN#	PIN NAME	TYPE	DESCRIPTION
1	VDD	PWR	Power supply, nominal 3.3V
2	DIF_IN	IN	0.7 V Differential TRUE input
3	DIF_IN#	IN	0.7 V Differential Complementary Input
4	GND	PWR	Ground pin.
5	OE0#	IN	Active low input for enabling DIF pair 0.
5		IIN	1 =disable outputs, 0 = enable outputs
6	DIF_0	OUT	0.7V differential true clock output
7	DIF_0#	OUT	0.7V differential Complementary clock output
8	VDD	PWR	Power supply, nominal 3.3V
9	GND	PWR	Ground pin.
10	OE1#	IN	Active low input for enabling DIF pair 1.
			1 =disable outputs, 0 = enable outputs
11	DIF_1	OUT	0.7V differential true clock output
12	DIF_1#	OUT	0.7V differential Complementary clock output
13	OE2#	IN	Active low input for enabling DIF pair 2.
			1 =disable outputs, 0 = enable outputs
14	DIF_2	OUT	0.7V differential true clock output
15	DIF_2#	OUT	0.7V differential Complementary clock output
16	GND	PWR	Ground pin.
17	VDD	PWR	Power supply, nominal 3.3V
18	OE3#	IN	Active low input for enabling DIF pair 3.
10	DIE 0	OUT	1 =disable outputs, 0 = enable outputs
19	DIF_3	OUT	0.7V differential true clock output
20	DIF_3#	OUT	0.7V differential Complementary clock output
21	OE4#	IN	Active low input for enabling DIF pair 4 1 =disable outputs, 0 = enable outputs
22	DIF_4	OUT	0.7V differential true clock output
23	DIF_4#	OUT	0.7V differential true clock output
24	VDD	PWR	Power supply, nominal 3.3V
25	GND	PWR	Ground pin.
25	GND	FWN	Active low input for enabling DIF pair 5.
26	OE5#	IN	1 =disable outputs, 0 = enable outputs
27	DIF_5	OUT	0.7V differential true clock output
28	DIF_5#	OUT	0.7V differential Complementary clock output
			This tri-level input selects one of 3 SMBus addresses. See the SMBus
29	**ADR_SEL	IN	Address Select Table for the addresses.
00	LUCII DW#	IAI	3.3V input for selecting PLL Band Width
30	HIGH_BW#	IN	0 = High, 1= Low
31	FS2	IN	Frequency select pin.
32	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant

Pin Description

PIN#	The state of the s							
	PIN NAME	TYPE	DESCRIPTION Date via of CMDLIC sirevitary 5 Visionard					
33	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant					
34	FS1	IN	3.3V Frequency select latched input pin.					
35	BYPASS#/PLL	IN	Input to select Bypass(fan-out) or PLL (ZDB) mode					
			0 = Bypass mode, 1= PLL mode VTTPWRGD# is an active low input used to sample latched inputs and					
			allow the device to Power Up. PD is an asynchronous active high input					
36	VTTPWRGD#/PD	IN	pin used to put the device into a low power state. The internal clocks and					
			PLLs are stopped.					
37	DIF_6#	OUT	0.7V differential complement clock output					
38	DIF_6	OUT	0.7V differential true clock output					
20		INI	Active low input for enabling DIF pair 6.					
39	OE6#	IN	1 = tri-state outputs, 0 = enable outputs					
40	GND	PWR	Ground pin.					
41	VDD	PWR	Power supply, nominal 3.3V					
42	DIF_7#	OUT	0.7V differential complement clock output					
43	DIF_7	OUT	0.7V differential true clock output					
44	OE7#	INI	Active low input for enabling DIF pair 7.					
44	OE7#	IN	1 = tri-state outputs, 0 = enable outputs					
45	DIF_8#	OUT	0.7V differential complement clock output					
46	DIF_8	OUT	0.7V differential true clock output					
47	OE8#	IN	Active low input for enabling DIF pair 8.					
47			1 = tri-state outputs, 0 = enable outputs					
48	VDD	PWR	Power supply, nominal 3.3V					
49	GND	PWR	Ground pin.					
50	DIF_9#	OUT	0.7V differential complement clock output					
51	DIF_9	OUT	0.7V differential true clock output					
52	OE9#	IN	Active low input for enabling DIF pair 9.					
			1 = tri-state outputs, 0 = enable outputs					
53	DIF_10#	OUT	0.7V differential complement clock output					
54	DIF_10	OUT	0.7V differential true clock output					
55	OE10#	IN	Active low input for enabling DIF pair 10.					
	OND	DWD	1 = tri-state outputs, 0 = enable outputs					
56	GND	PWR	Ground pin.					
57	VDD	PWR	Power supply, nominal 3.3V					
58	DIF_11#	OUT	0.7V differential complement clock output					
59	DIF_11	OUT	0.7V differential true clock output Active low input for enabling DIF pair 11.					
60	OE11#	IN	1 = tri-state outputs, 0 = enable outputs					
61	FS0	IN	3.3V Frequency select latched input pin.					
01	1.00	11 N	This pin establishes the reference current for the differential current-					
			mode output pairs. This pin requires a fixed precision resistor tied to					
62	IREF	OUT	ground in order to establish the appropriate current. 475 ohms is the					
			standard value.					
63	AGND	PWR	Analog Ground pin for Core PLL					
64	VDDA	PWR	3.3V power for the PLL core.					
		•						

Absolute Max

Symbol	Parameter	Min	Max	Units
VDDA	3.3V Core Supply Voltage		4.6	V
VDD	3.3V Logic Supply Voltage		4.6	V
V_{IL}	Input Low Voltage	GND-0.5		V
V_{IH}	Input High Voltage		V _{DD} +0.5V	V
Ts	Storage Temperature	-65	150	°C
Tambient	Ambient Operating Temp	0	70	°C
Tcase	Case Temperature		115	°C
	Input ESD protection			
ESD prot	human body model	2000		V

Electrical Characteristics - Input/Supply/Common Output Parameters

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD} = 3.3 \text{ V } +/-5\%$

· A · · · · · · · · · · · · · · · · · ·	9 00						
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V _{IH}	3.3 V +/-5%	2		V _{DD} + 0.3	٧	1
Input Low Voltage	V_{IL}	3.3 V +/-5%	GND - 0.3		0.8	V	1
Input High Current	I _{IH}	$V_{IN} = V_{DD}$	-5		5	uA	1
Input Low Current	I _{IL1}	$V_{IN} = 0 \text{ V}$; Inputs with no pull-up resistors	-5			uA	1
imput Low Guiterit	I _{IL2}	$V_{IN} = 0 \text{ V}$; Inputs with pull-up resistors	-200			uA	1
Operating Supply Current	I _{DD3.3OP}	Full Active, $C_L = Full load$;			375	mA	1
Powerdown Current	I _{DD3.3PD}	all differential pairs tri-stated			24	mΑ	1
Input Fraguency	F _{iPLL}	PLL Mode	100		400	MHz	1
Input Frequency	F _{iBYPASS}	Bypass Mode	33		400	MHz	1
Pin Inductance	L _{pin}				7	nΗ	1
Consoitance	C _{IN}	Logic Inputs	1.5		5	рF	1
Capacitance	C _{OUT}	Output pin capacitance			6	рF	1
PLL Jitter Peaking	ineur	Peaking when HIGH_BW#=0		1.5	2	dB	1
FLL Jiller Feaking	ĴРЕАК	Peaking when HIGH_BW#=1		1.5	2	dB	1
PLL Bandwidth	BW	PLL Bandwidth when HIGH_BW#=0	2	3	4	MHz	1
1 LL Bandwidth	DVV	PLL Bandwidth when HIGH_BW#=1	0.7	1	1.4	MHz	1
		From V _{DD} Power-Up and after input					
Clk Stabilization	T _{STAB}	clock stabilization or de-assertion of PD# to 1st clock			1.8	ms	1,2
Modulation Frequency	f _{MOD}	Triangular Modulation	30		33	kHz	1
OE# Latency	t _{LATOE} #	DIF start after OE# assertion DIF stop after OE# deassertion	4		12	cycles	1,3
Tdrive_PD	t _{DRVPD}	DIF output enable after PD de-assertion			300	us	1,3
Tfall	t _F	Fall time of OE#			5	ns	1
Trise	t _R	Rise time of OE#			5	ns	1

¹Guaranteed by design and characterization, not 100% tested in production.

²See timing diagrams for timing requirements.

³Time from deassertion until outputs are >200 mV

Electrical Characteristics - Clock Input Parameters

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD} = 3.3 \text{ V } +/-5\%$

A = 0 70 G; Gappiy Voltago V _{DD} = 0.0 V 17 G/G							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V _{IHDIF}	Differential inputs (single-ended measurement)	600	800	1150	mV	1
Input Low Voltage - DIF_IN	V_{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1
Input Common Mode Voltage - DIF_IN	V_{COM}	Common Mode Input Voltage	300		1000	mV	1
Input Amplitude - DIF_IN	V_{SWING}	Peak to Peak value	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}$, $V_{IN} = GND$	-5		5	uA	1
Input Duty Cycle	d _{tin}	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		125	ps	1

¹ Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics - DIF 0.7V Current Mode Differential Pair

 $T_A = 0 - 70$ °C; $V_{DD} = 3.3 \text{ V +/-5\%}$; $C_L = 2pF$, $R_S = 33.2\Omega$, $R_P = 49.9\Omega$, $R_{REF} = 475\Omega$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo ¹	$V_O = V_x$	3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended	660		850	m)/	1,3
Voltage Low	VLow	signal using oscilloscope math function.	-150		150	mV	1,3
Max Voltage	Vovs	Measurement on single ended signal			1150	ma\/	1
Min Voltage	Vuds	using absolute value.	-300			mV	1
Crossing Voltage (abs)	Vcross(abs)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Long Accuracy	ppm	see Tperiod min-max values			0	ppm	1,2
Rise Time	t _r	$V_{OL} = 0.175V, V_{OH} = 0.525V$	175		700	ps	1
Fall Time	t _f	$V_{OH} = 0.525 V V_{OL} = 0.175 V$	175		700	ps	1
Rise Time Variation	d-t _r				125	ps	1
Fall Time Variation	d-t _f				125	ps	1
Duty Cycle	d _{t3}	Measurement from differential wavefrom	45		55	%	1
Skew, Input to Output	t _{pdBYP}	Bypass Mode, V _T = 50%	2.5		4.5	ps	1
Skew, input to Output	t _{pdPLL}	PLL Mode $V_T = 50\%$	-250		250	ps	1
Skew, Output to Output	t _{sk3}	V _T = 50%			50	ps	1
Jitter, Cycle to cycle	t.	PLL mode			50	ps	1,5
Jitter, Cycle to cycle	t _{jcyc-cyc}	BYPASS mode as additive jitter			50	ps	1,5

¹Guaranteed by design and characterization, not 100% tested in production.

IDT® Twelve Output Differential Buffer for PCle Gen1/Gen2, QPI, and FBDIMM

²Slew rate measured through Vswing min centered around differential zero

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK410B+/CK509B accuracy requirements. The 9DB1200 itself does not contribute to ppm error.

 $^{^{3}}I_{REF} = V_{DD}/(3xR_{R})$. For $R_{R} = 475\Omega$ (1%), $I_{REF} = 2.32$ mA. $I_{OH} = 6$ x I_{REF} and $V_{OH} = 0.7$ V @ $Z_{O} = 50\Omega$.

⁴ Applies to Bypass Mode Only

⁵ Measured from differential waveform

Electrical Characteristics - Phase Jitter

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP.	MAX	UNITS	NOTES
		PCIe Gen 1 REFCLK phase jitter (including PLL BW 8 - 16 MHz, ζ = 0.54, Td=10 ns, Ftrk=1.5 MHz)		35	86	ps	1,2,3
Jitter, Phase	tjphase	PCIe Gen 2 REFCLK phase jitter (including PLL BW 8 - 16 MHz,		1.1	3	ps rms	1,2
		PCIe Gen 2 REFCLK phase jitter (including PLL BW 8 - 16 MHz, ζ = 0.54, Td=12 ns) Hi-band content (1.5MHz to Nyquist)		2.3	3.1	ps rms	1,2
		QPI specs REFCLK phase jitter		0.25	0.5	ps rms	2,4

Notes on Phase Jitter:

¹ See http://www.pcisig.com for complete specs. Guaranteed by design and characterization, not tested in production.

² Device driven by 932S421BGLF or equivalent

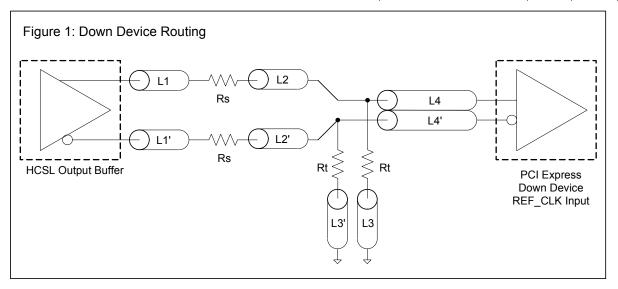
³ BER of 1E-9

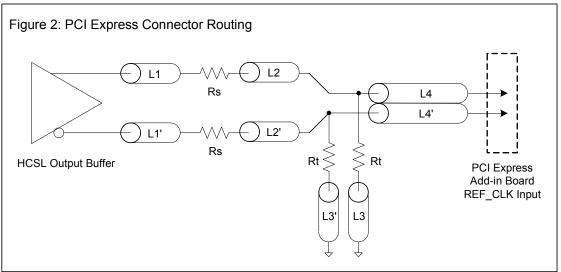
⁴ Measured at 133MHz using CSI_133_MHZ_6_4BG_12UI template in Intel supplied Clock Jitter Tool.

DIF Reference Clock							
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure				
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1				
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1				
Rs	33	ohm	1				
Rt	49.9	ohm	1				

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

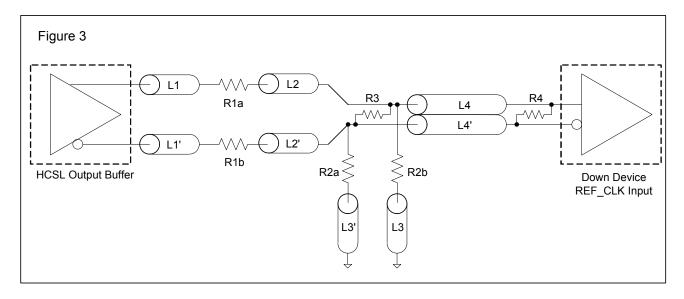
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



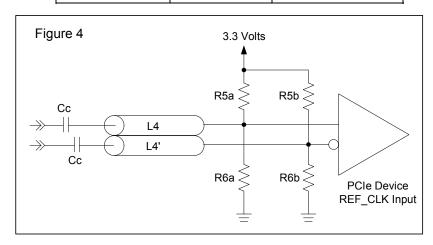


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)							
Vdiff	Vp-p	Vcm	R1	R2	R3	R4	Note	
0.45v	0.22v	1.08	33	150	100	100		
0.58	0.28	0.6	33	78.7	137	100		
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible	
0.60	0.3	1.2	33	174	140	100	Standard LVDS	

R1a = R1b = R1 R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)							
Component	Value	Note					
R5a, R5b	8.2K 5%						
R6a, R6b	1K 5%						
Сс	0.1 μF						
Vcm	0.350 volts						



General SMBus serial interface information for the 9DB1200C

How to Write:

- · Controller (host) sends a start bit.
- Controller (host) sends the write address DC_(n)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) sends the data byte count = X
- ICS clock will acknowledge
- Controller (host) starts sending Byte N through Byte N + X -1
- ICS clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

Ind	ex Block W	/rit	e Operation
Cor	ntroller (Host)		ICS (Slave/Receiver)
Т	starT bit		
Slav	e Address DC _(h)		
WR	WRite		
			ACK
Begi	nning Byte = N		
			ACK
Data	Byte Count = X		
			ACK
Begir	nning Byte N		
			ACK
	\Diamond	'te	
	\Diamond	X Byte	\Diamond
	\rightarrow	×	\Q
			\Diamond
Byte	e N + X - 1		
		ACK	
Р	stoP bit		

How to Read:

- · Controller (host) will send start bit.
- Controller (host) sends the write address DC (h)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address DD (h)
- ICS clock will acknowledge
- ICS clock will send the data byte count = X
- ICS clock sends Byte N + X -1
- ICS clock sends Byte 0 through byte X (if X_(h) was written to byte 8).
- · Controller (host) will need to acknowledge each byte
- · Controllor (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

Ind	ex Block Rea	ad	Operation		
Con	troller (Host)	IC	S (Slave/Receiver)		
T	starT bit				
Slave	e Address DC _(h)				
WR	WRite				
			ACK		
Begir	nning Byte = N				
			ACK		
RT	Repeat starT				
Slave	e Address DD _(h)				
RD	ReaD				
		ACK			
		Data Byte Count = X			
	ACK				
			Beginning Byte N		
	ACK				
		X Byte	\Q		
	Q	Ø,	\Q		
	\Diamond	×	\Q		
	\Q				
			Byte N + X - 1		
N	Not acknowledge				
Р	stoP bit				

Note: Addresses show assumes pin 29 is low.

SMBus Table: Frequency Select Register

Byt	Byte 0 Pin # Name		Name	Control Function	Type	0	1	PWD
Bit 7		-	HIGH_BW#	High or Low BW	RW	High BW	Low BW	Latch
Bit 6		-	BYPASS#/PLL	Bypass (non-PLL Mode) or PLL Mode	RW	Bypass	PLL	Latch
Bit 5		-	Reserved	Reserved	RW	Reserved		Χ
Bit 4		- Reserved		Reserved	RW	RW Reserved		Χ
Bit 3		-	Reserved	red Reserved		Rese	erved	Χ
Bit 2		-	FS2	Frequency Select 2	RW			Latch
Bit 1		- FS1		Frequency Select 1		See FS Table		Latch
Bit 0		-	FS0	Frequency Select 0	RW			Latch

SMBus Table: Output Control Register

Byt	e 1	Pin #	Name	Control Function	Туре	0	1	PWD
Bit 7	43	3,42	DIF_7	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 6	38	3,37	DIF_6	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 5	2	7,28	DIF_5	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 4	2	2,23	DIF_4	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 3	19	9,20	DIF_3	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 2	14	4,15	DIF_2	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 1	1	1,12	DIF_1	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 0	(3,7	DIF_0	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1

SMBus Table: Output Control Register

Byte	e 2 Pin #	Name	Control Function		0	1	PWD
Bit 7	7 - Reserved Reserved RW Re		Rese	erved	0		
Bit 6	-	Reserved	Reserved	RW	Rese	erved	0
Bit 5	-	Reserved	Reserved	RW	Rese	erved	0
Bit 4	-	Reserved	Reserved	RW	Rese	Reserved	
Bit 3	58,59	DIF_11	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 2	53,54	DIF_10	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 1	50,51	DIF_9	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1
Bit 0	45,46	DIF_8	Output Control (Disable = Hi-Z)	RW	Disable	Enable	1

SMBus Table: Output Enable Readback

Byt	e 3	Pin #	Name	Control Function	Туре	0	1	PWD
Bit 7	43	3,42	OE7#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 6	38	3,37	OE6#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 5	27	7,28	OE5#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 4	22	2,23	OE4#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 3	19	9,20	OE3#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 2	14	4,15	OE2#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 1	1	1,12	OE1#	OE# Pin Readback	R	Enabled	Disabled	Χ
Bit 0	(6,7	OE0#	OE# Pin Readback	R	Enabled	Disabled	Χ

SMBus Table: Output Enable Readback

Byt	Byte 4 Pin # Name		Name	Control Function		0	1	PWD
Bit 7		-	Reserved	Reserved	R	Reserved		0
Bit 6		-	Reserved	Reserved	R	Rese	erved	0
Bit 5		-	Reserved	Reserved	R	Rese	erved	0
Bit 4		-	Reserved	Reserved	R	Reserved		0
Bit 3	58	3,59	OE11#	Output Control (Disable = Hi-Z)	R	Enabled	Disabled	Χ
Bit 2	53	3,54	OE10#	Output Control (Disable = Hi-Z)	R	Enabled	Disabled	Χ
Bit 1	50),51	OE9#	Output Control (Disable = Hi-Z)	R	Enabled	Disabled	Χ
Bit 0	45	5,46	OE8#	Output Control (Disable = Hi-Z)	R	Enabled	Disabled	Χ

Note: For an output to be enabled, BOTH the Output Enable Bit and the OE# pin must be enabled. This means that the Output Enable Bit must be '1' and the corresponding OE# pin must be '0'.

SMBus Table: Vendor & Revision ID Register

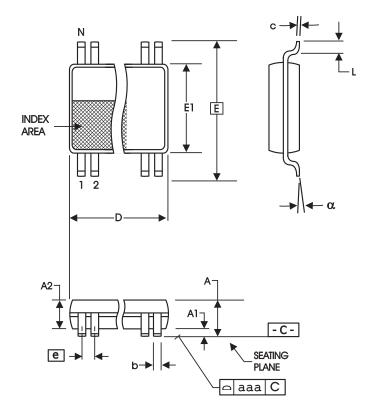
Byte	5 Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	RID3	REVISION ID	R	1	-	Χ
Bit 6	-	RID2		R	ı	-	Χ
Bit 5	-	RID1		R	-	-	Х
Bit 4	-	RID0		R	-	-	Х
Bit 3	-	VID3		R	-	-	0
Bit 2	-	VID2	VENDOB ID	R	ı	-	0
Bit 1	-	VID1	VENDOR ID	R	-	-	1
Bit 0	-	VID0		R	-	-	0

SMBus Table: DEVICE ID

Byte	6 Pin #	Name	Control Function	Туре	0	1	PWD
Bit 7	-		Device ID 7 (MSB)	RW			0
Bit 6	-		Device ID 6	RW			0
Bit 5	-		Device ID 5	RW			0
Bit 4	-		Device ID 4	RW	Davias ID	is 0C Hex	0
Bit 3	-		Device ID 3	RW	Device in	is uc nex	1
Bit 2	-		Device ID 2	RW			1
Bit 1	-		Device ID 1	RW			0
Bit 0	-		Device ID 0	RW			0

SMBus Table: Byte Count Register

Byte	e 7 Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	BC7		RW	-	-	0
Bit 6	-	BC6		RW	-	-	0
Bit 5	-	BC5		RW	-	-	0
Bit 4	-	BC4	Writing to this register configures how	RW	-	-	0
Bit 3	-	BC3	many bytes will be read back.	RW	-	-	0
Bit 2	-	BC2		RW	-	-	1
Bit 1	-	BC1		RW	-	-	1
Bit 0	-	BC0		RW	-	-	1



6.10 mm. Body, 0.50 mm. Pitch TSSOP (240 mil) (20 mil)

	(240 11111)	(20 11111)			
	In Milli	meters	In In	ches	
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
Α		1.20		.047	
A1	0.05	0.15	.002	.006	
A2	0.80	1.05	.032	.041	
b	0.17	0.27	.007	.011	
С	0.09	0.20	.0035	.008	
D	SEE VAF	RIATIONS	SEE VARIATIONS		
E	8.10 BASIC		0.319 BASIC		
E1	6.00	6.20	.236	.244	
е	0.50 BASIC		0.020 BASIC		
L	0.45	0.75	.018	.030	
N	N SEE VARIATIONS		SEE VARIATIONS		
α	0°	8°	0°	8°	
aaa		0.10		.004	

VARIATIONS

N	D mm.		D (inch)		
	IN IN	MIN	MAX	MIN	MAX
	64	16.90	17.10	.665	.673

Reference Doc.: JEDEC Publication 95, MO-153

10-0039

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DB1200CGLF	Tubes	64-pin TSSOP	0 to +70°C
9DB1200CGLFT	Tape and Reel	64-pin TSSOP	0 to +70°C

[&]quot;LF" after the package code denotes the Pb-Free configuration, RoHS compliant.

9DB1200C Twelve Output Differential Buffer for PCle Gen1/Gen2, QPI, and FBDIMM

Revision History

Rev.	Issue Date	Description	Page #
		1. Updated SMBus Serial Interface Information.	
Α	12/18/2007	2. Release to Final.	10
В	4/7/2008	Added Input Clock Parameters	6
		1. Updated Phase Jitter Numbers	
		2. Added PLL BW and jitter peaking specs	
		3. Added input to output delay specs	
С	8/28/2008	5. Updated stabilization time to 1.8ms from 1.0ms	
		1. Corrected pin number references in SMBus Bytes 1 and 3	
D	9/15/2009	2. Added typical values to phase jitter table.	Various
Е	11/4/2009	Changed CLK Stabilization spec from 1.0 to 1.8 ms	5
F	7/1/2010	Corrected power groups table for input clock,	2
G	8/15/2012	Updated Byte 5 VENDOR ID (bits 3 through 0) from 0001 to 0010	12

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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